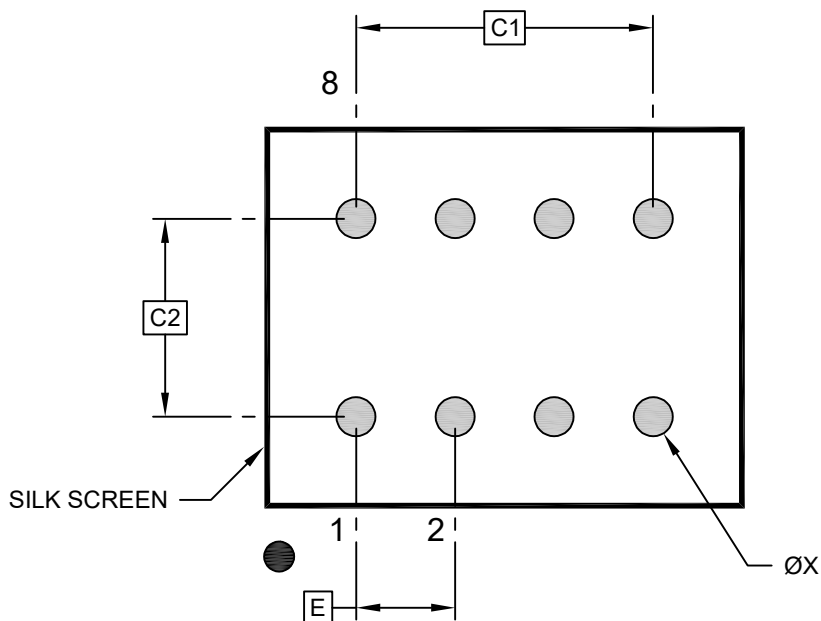


8-Ball Very Thin Fine-Pitch Ball Grid Array Package (E8B) - 1.50x2.00x0.85 mm Body [VFBGA] ; Atmel Global Package Code GXU

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1	1.50 BSC		
Contact Pad Spacing	C2	1.00 BSC		
Contact Pad Width (X8)	X			0.20

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.